

## SN74LVC244A 3 ステート出力、オクタール・バッファ/ドライバ

### 1 特長

- 1.65 V ~ 3.6 V で動作
- 5.5V までの入力電圧に対応
- $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$  と  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$  で仕様が規定されています
- 最大  $t_{pd}$  5.9ns (3.3 V 時)
- 標準  $V_{OLP}$  (出力グランド・バウンス)  $< 0.8\text{V}$  ( $V_{CC} = 3.3\text{V}$ ,  $T_A = 25^{\circ}\text{C}$ )
- 標準  $V_{OHV}$  (出力  $V_{OH}$  アンダーシュート)  $> 2\text{V}$  ( $V_{CC} = 3.3\text{V}$ ,  $T_A = 25^{\circ}\text{C}$ )
- すべてのポートでミクスモード・シグナル動作をサポート (3.3V  $V_{CC}$  で 5V の入力または出力電圧)
- $I_{off}$  により活線挿抜、部分的パワーダウン・モード、バック・ドライブ保護をサポート
- 最高 5.5V の入力を  $V_{CC}$  レベルに変換する降圧トランスレータとして使用可能
- 超小型ロジック QFN パッケージ (最大高さ 0.5mm) で供給
- JESD 17 準拠で 250mA 超のラッチアップ性能
- JESD 22 を超える ESD 保護
  - 人体モデルで 2000V
  - 荷電デバイス・モデルで 1000V

### 2 アプリケーション

- サーバー
- LED ディスプレイ
- ネットワーク・スイッチ
- 通信インフラ
- モーター・ドライバ
- I/O エクスパンダ

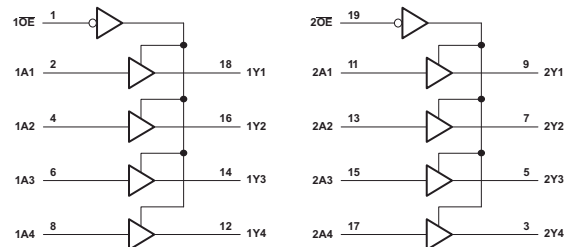
### 3 概要

これらのオクタール・バス・バッファは、1.65V ~ 3.6V の  $V_{CC}$  で動作するように設計されています。SN74LVC244A デバイスは、データ・バス間の非同期通信用に設計されています。

#### 製品情報

型番	パッケージ <sup>(1)</sup> (1 ページ)	本体サイズ (公称)
SN74LVC244AN	PDIP (20)	25.40mm × 6.35mm
SN74LVC244ANS	SO (20)	12.60mm × 5.30mm
SN74LVC244ADB	SSOP (20)	7.50mm × 5.30mm
SN74LVC244ADGV	TVSOP (20)	5.00mm × 4.40mm
SN74LVC244ADW	SOIC (20)	12.80mm × 7.50mm
SN74LVC244ARGY	VQFN (20)	4.50mm × 3.50mm
SN74LVC244AZQN	BGA (20)	3.00mm × 4.00mm
SN74LVC244APW	TSSOP (20)	6.50mm × 4.40mm
SN74LVC244ARWP	X1QFN (20)	2.50mm × 3.30mm

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



Pin numbers shown are for the DB, DGV, DW, N, NS, PW, and RGY packages.

#### 論理図 (正論理)



## Table of Contents

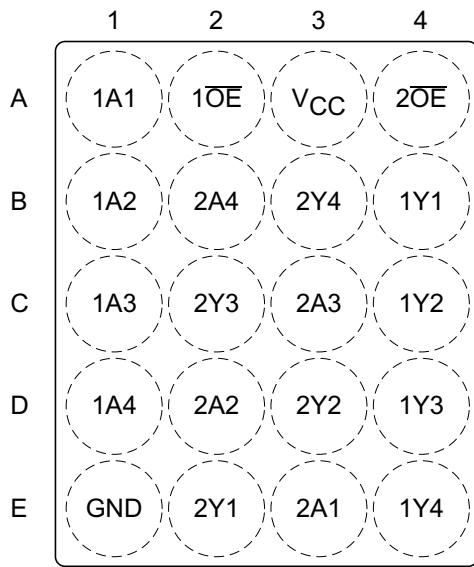
<b>1 特長</b> .....	1	8.3 Feature Description.....	11
<b>2 アプリケーション</b> .....	1	8.4 Device Functional Modes.....	11
<b>3 概要</b> .....	1	<b>9 Application and Implementation</b> .....	12
<b>4 Revision History</b> .....	2	9.1 Application Information.....	12
<b>5 Pin Configuration and Functions</b> .....	3	9.2 Typical Application.....	12
<b>6 Specifications</b> .....	5	<b>10 Power Supply Recommendations</b> .....	13
6.1 Absolute Maximum Ratings.....	5	<b>11 Layout</b> .....	14
6.2 ESD Ratings.....	5	11.1 Layout Guidelines.....	14
6.3 Recommended Operating Conditions.....	6	11.2 Layout Example.....	14
6.4 Thermal Information.....	6	<b>12 Device and Documentation Support</b> .....	15
6.5 Electrical Characteristics.....	7	12.1 Receiving Notification of Documentation Updates..	15
6.6 Switching Characteristics.....	8	12.2 Support Resources.....	15
6.7 Operating Characteristics.....	8	12.3 Trademarks.....	15
6.8 Typical Characteristics.....	9	12.4 Electrostatic Discharge Caution.....	15
<b>7 Parameter Measurement Information</b> .....	10	12.5 Glossary.....	15
<b>8 Detailed Description</b> .....	11	<b>13 Mechanical, Packaging, and Orderable Information</b> .....	15
8.1 Overview.....	11		
8.2 Functional Block Diagram.....	11		

## 4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

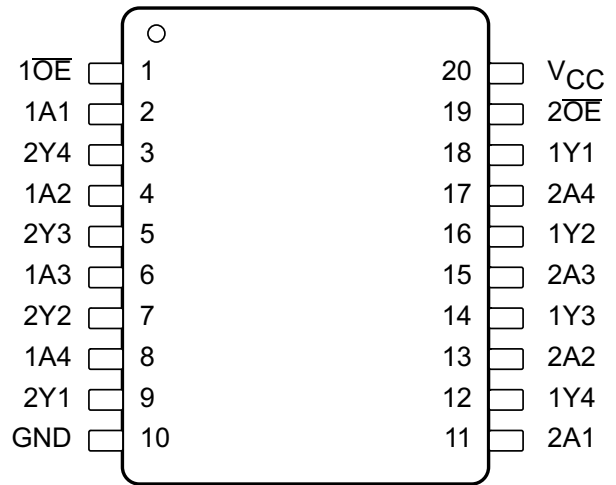
Changes from Revision AB (November 2016) to Revision AC (October 2020)	Page
• 文書全体にわたって表、図、相互参照の採番方法を更新.....	1
Changes from Revision AA (June 2016) to Revision AB (November 2016)	Page
• Changed A2 to A4 for 2 $\overline{OE}$ in <i>Pin Functions</i> table.....	3
• Added ambient temperature, $T_A$ for BGA package and all other packages in <i>Recommended Operating Conditions</i> .....	6
Changes from Revision Z (January 2015) to Revision AA (May 2016)	Page
• 提供しているすべてのパッケージを表示するように、「デバイス情報」の表を更新.....	1
• Added RWP Package .....	3
• Deleted GQN package from <i>Pin Functions</i> table.....	3
• Added RWP thermal information to <i>Thermal Information</i> table and updated all thermal information for existing packages.....	6
• Updated all values for ZQN column in <i>Thermal Information</i> table.....	6
• Added package type in <i>Thermal Information</i> table.....	6
Changes from Revision Y (September 2010) to Revision Z (January 2015)	Page
• 「アプリケーション」セクション、「製品情報」表、「ESD 定格」表、「熱に関する情報」表、「代表的特性」セクション、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加.....	1
• 「注文情報」表を削除 (このデータシートの末尾にある「メカニカル、パッケージ、および注文情報」を参照)	1
• 「特長」を更新.....	1

### 5 Pin Configuration and Functions



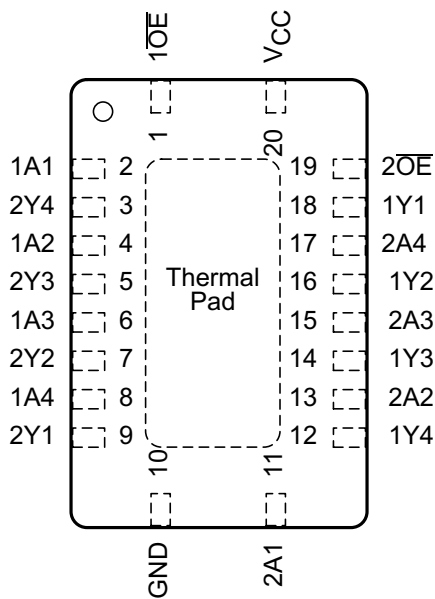
Not to scale

5-1. ZQN Package 20-Pin BGA Top View



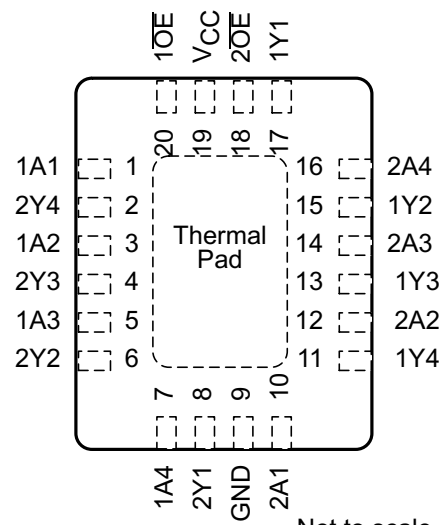
Not to scale

5-2. DB, DGV, DW, N, NS, and PW Packages 20-Pin SSOP, TVSOP, SOIC, PDIP, SO, and TSSOP Front View



Not to scale

5-3. RGY Package 20-Pin VQFN Top View



Not to scale

5-4. RWP Package 20-Pin X1QFN Top View

表 5-1. Pin Functions

NAME	PIN			TYPE	DESCRIPTION
	DB, DGV, DW, N, NS, PW, and RGY	ZQN	RWP		
1A1	2	A1	1	I	Port 1 A1 input
1A2	4	B1	3	I	Port 1 A2 input
1A3	6	C1	5	I	Port 1 A3 input
1A4	8	D1	7	I	Port 1 A4 input
1 $\overline{OE}$	1	A2	20	I	Output enable
1Y1	18	B4	17	O	Port 1 Y1 output
1Y2	16	C4	15	O	Port 1 Y2 output
1Y3	14	D4	13	O	Port 1 Y3 output
1Y4	12	E4	11	O	Port 1 Y4 output
2A1	11	E3	10	I	Port 2 A1 input
2A2	13	D2	12	I	Port 2 A2 input
2A3	15	C3	14	I	Port 2 A3 input
2A4	17	B2	16	I	Port 2 A4 input
2 $\overline{OE}$	19	A4	18	I	Output enable
2Y1	9	E2	8	O	Port 2 Y1 output
2Y2	7	D3	6	O	Port 2 Y2 output
2Y3	5	C2	4	O	Port 2 Y3 output
2Y4	3	B3	2	O	Port 2 Y4 output
GND	10	E1	9	—	Ground
V <sub>CC</sub>	20	A3	19	—	Power pin

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	-0.5	6.5	V	
V <sub>I</sub>	Input voltage <sup>(2)</sup>	-0.5	6.5	V	
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	6.5	V	
V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2) (3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-50	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	-50	mA	
I <sub>O</sub>	Continuous output current		±50	mA	
	Continuous current through V <sub>CC</sub> or GND		±100	mA	
P <sub>tot</sub>	Power dissipation	T <sub>A</sub> = -40°C to +125°C <sup>(4) (5)</sup>	500	mW	
T <sub>J</sub>	Junction temperature		150	°C	
T <sub>stg</sub>	Storage temperature		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [セクション 6.3](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the [セクション 6.3](#) table.
- (4) For the DW package: above 70°C the value of P<sub>tot</sub> derates linearly with 8 mW/K.
- (5) For the DB, DGV, N, NS, and PW packages: above 60°C the value of P<sub>tot</sub> derates linearly with 5.5 mW/K.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge		V
	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	
	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		T <sub>A</sub> = 25°C		–40 TO +85°C		–40 TO +125°C		UNIT		
		MIN	MAX	MIN	MAX	MIN	MAX			
V <sub>CC</sub>	Supply voltage	Operating		1.65	3.6	1.65	3.6	1.65	3.6	V
		Data retention only		1.5		1.5		1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V		1.7		1.7		1.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V		2		2		2		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7		0.7		0.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		0.8		0.8		
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V		–4		–4		–4		mA
		V <sub>CC</sub> = 2.3 V		–8		–8		–8		
		V <sub>CC</sub> = 2.7 V		–12		–12		–12		
		V <sub>CC</sub> = 3 V		–24		–24		–24		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		4		4		4		mA
		V <sub>CC</sub> = 2.3 V		8		8		8		
		V <sub>CC</sub> = 2.7 V		12		12		12		
		V <sub>CC</sub> = 3 V		24		24		24		
T <sub>A</sub>	Ambient temperature	BGA package		–40		85				°C
		All other packages						–40 125		

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See [Implications of Slow or Floating CMOS Inputs](#), SCBA004.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74LVC244A									UNIT
		DB <sup>(2)</sup> (SSOP)	DGV <sup>(2)</sup> (TVSOP)	DW <sup>(2)</sup> (SOIC)	ZQN <sup>(2)</sup> (BGA)	N <sup>(2)</sup> (PDIP)	NS <sup>(2)</sup> (SO)	PW <sup>(2)</sup> (TSSOP)	RGY <sup>(3)</sup> (VQFN)	RWP <sup>(3)</sup> (X1QFN)	
		20 PINS									
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	108.1	128.7	90.9	198.7	61.6	90.1	114.7	50.3	79.9	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	70.2	43.7	55.3	106.8	46.5	56.4	48.4	58.4	63.2	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	63.3	70.2	58.8	143.1	42.5	57.7	65.6	28.3	46.4	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	30.6	3.1	29.1	24.1	34.6	28.4	6.8	4.9	2.6	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	62.9	69.5	58.3	119.6	42.4	57.2	65.1	28.4	46.3	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	—	—	—	n/a	—	—	—	22.7	27.3	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

(2) The package thermal impedance is calculated in accordance with JESD 51-7.

(3) The package thermal impedance is calculated in accordance with JESD 51-5.

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			–40 TO +85°C		–40 TO +125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = –100 μA	1.65 V to 3.6 V	V <sub>CC</sub> – 0.2			V <sub>CC</sub> – 0.2		V <sub>CC</sub> – 0.3		V
	I <sub>OH</sub> = –4 mA	1.65 V	1.29			1.2		1.05		
	I <sub>OH</sub> = –8 mA	2.3 V	1.9			1.7		1.55		
	I <sub>OH</sub> = –12 mA	2.7 V	2.2			2.2		2.05		
		3 V	2.4			2.4		2.25		
I <sub>OH</sub> = –24 mA	3 V	2.3			2.2		2			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.1			0.2		0.3		V
	I <sub>OL</sub> = 4 mA	1.65 V	0.24			0.45		0.6		
	I <sub>OL</sub> = 8 mA	2.3 V	0.3			0.7		0.75		
	I <sub>OL</sub> = 12 mA	2.7 V	0.4			0.4		0.6		
	I <sub>OL</sub> = 24 mA	3 V	0.55			0.55		0.8		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V	±1			±5		±20		μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0	±1			±10		±20		μA
I <sub>OZ</sub>	V <sub>O</sub> = 0 to 5.5 V	3.6 V	±1			±10		±20		μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	1			10		40		μA
	3.6 V ≤ V <sub>I</sub> ≤ 5.5 V <sup>(1)</sup>		1			10		40		
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500			500		5000		μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	4							pF
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V	5.5							pF

(1) This applies in the disabled state only.

## 6.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			–40 TO +85°C		–40 TO +125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	1.5 V	1	7	14.4	1	14.9	1	16.4	ns
			1.8 V ± 0.15 V	1	5.9	10.4	1	10.9	1	12.4	
			2.5 V ± 0.2 V	1	4.2	7.4	1	7.9	1	10	
			2.7 V	1	4.2	6.7	1	6.9	1	8.2	
			3.3 V ± 0.3 V	1.5	3.9	5.7	1.5	5.9	1.5	7.2	
t <sub>en</sub>	OE	Y	1.5 V	1	8.3	17.8	1	18.3	1	19.8	ns
			1.8 V ± 0.15 V	1	6.4	12.1	1	12.6	1	14.1	
			2.5 V ± 0.2 V	1	4.6	9.1	1	9.6	1	11.7	
			2.7 V	1	5	8.4	1	8.6	1	10.3	
			3.3 V ± 0.3 V	1.5	4.5	7.4	1.5	7.6	1.5	9.4	
t <sub>dis</sub>	OE	Y	1.5 V	1	7.2	15.6	1	16.1	1	17.6	ns
			1.8 V ± 0.15 V	1	5.8	11.6	1	12.1	1	13.6	
			2.5 V ± 0.2 V	1	3.7	7.3	1	7.8	1	9.9	
			2.7 V	1	3.8	6.6	1	6.8	1	8.6	
			3.3 V ± 0.3 V	1.5	3.8	6.3	1.5	6.5	1.5	8	
t <sub>sk(o)</sub>			3.3 V ± 0.3 V				1		1.5	ns	

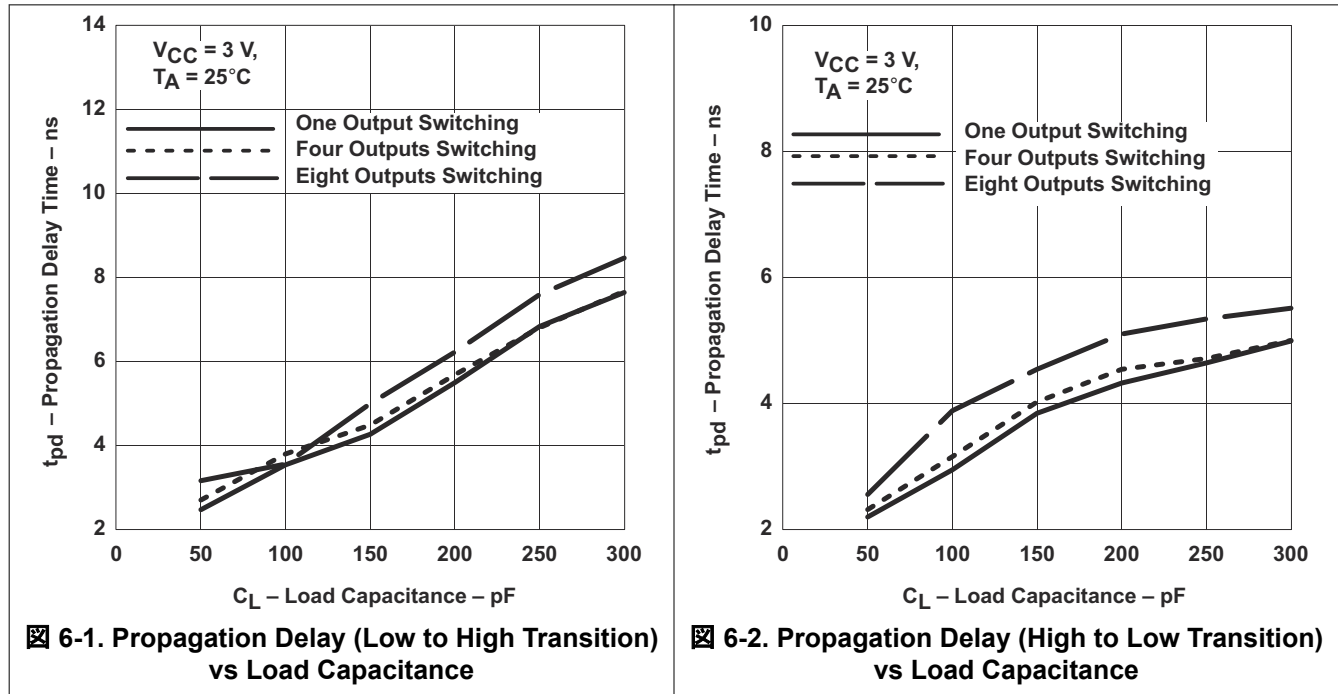
## 6.7 Operating Characteristics

T<sub>A</sub> = 25°C

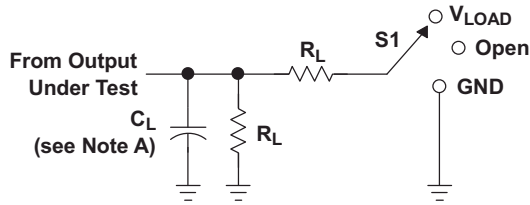
PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT	
C <sub>pd</sub>	Power dissipation capacitance per buffer/driver	Outputs enabled	f = 10 MHz	1.8 V	43	pF
				2.5 V	43	
				3.3 V	44	
	Outputs disabled	f = 10 MHz	1.8 V	1		
			2.5 V	1		
			3.3 V	2		



## 6.8 Typical Characteristics



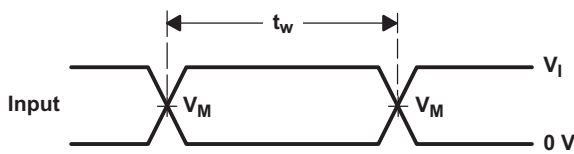
## 7 Parameter Measurement Information



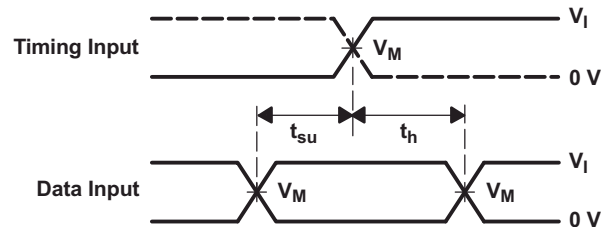
LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

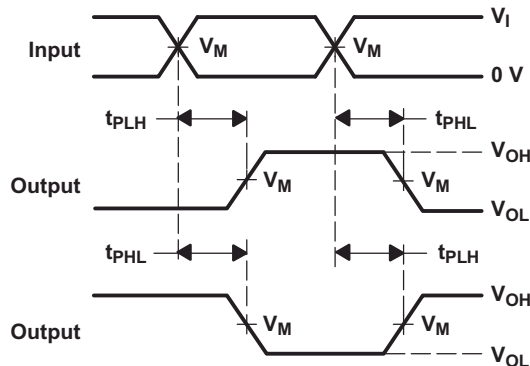
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
1.5 V	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.1 V
$1.8 V \pm 0.15 V$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 V \pm 0.2 V$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3 V \pm 0.3 V$	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



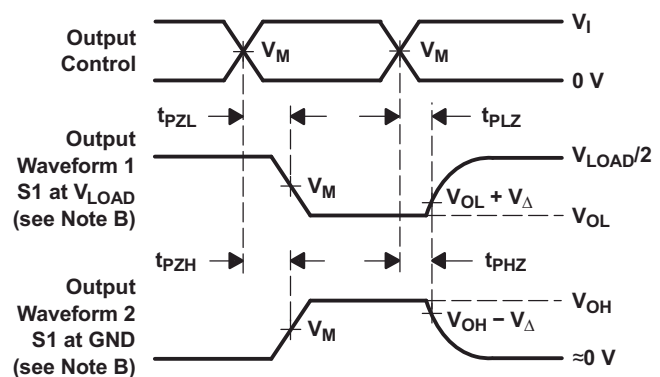
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10$  MHz,  $Z_O = 50 \Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

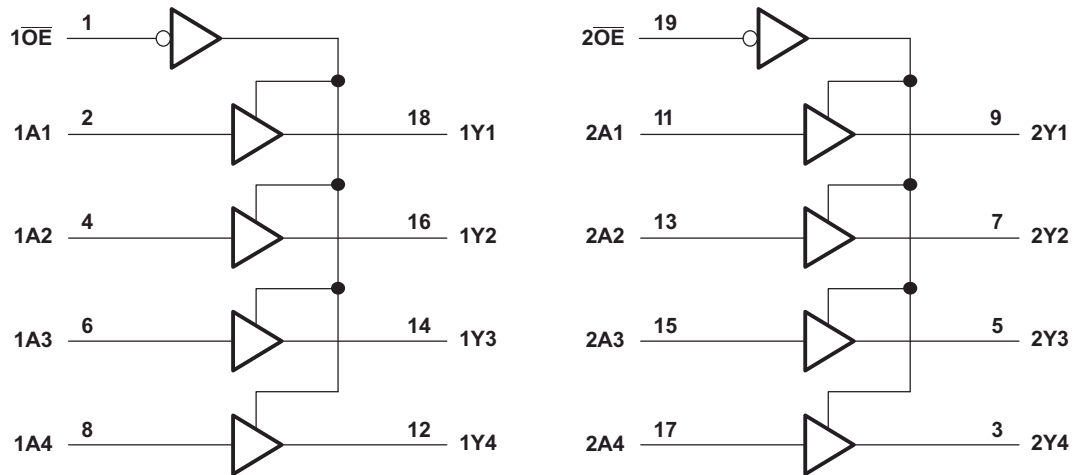
### 7-1. Load Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

The SN74LVC244A device is organized as two 4-bit buffers/line drivers with separate output-enable ( $\overline{OE}$ ) inputs. The device passes data from the A inputs to the Y outputs when  $\overline{OE}$  is low. The outputs are in the high-impedance state when  $\overline{OE}$  is high.  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor to ensure the high-impedance state during power up or power down; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### 8.2 Functional Block Diagram



Pin numbers shown are for the DB, DGV, DW, N, NS, PW, and RGY packages.

图 8-1. Logic Diagram (Positive Logic)

### 8.3 Feature Description

- Allows down voltage translation
  - 5 V to 3.3 V
  - 5 V or 3.3 V to 1.8 V
- Inputs accept voltage levels up to 5.5 V
- It is available in ultra small logic 20 pin QFN package at 0.5 mm max height with 0.4 mm pitch.

### 8.4 Device Functional Modes

表 8-1 lists the functional modes of the SN74LVC244A.

表 8-1. Function Table

INPUTS		OUTPUT Y
OE	A	
L	H	H
L	L	L
H	X	Hi-Z

## 9 Application and Implementation

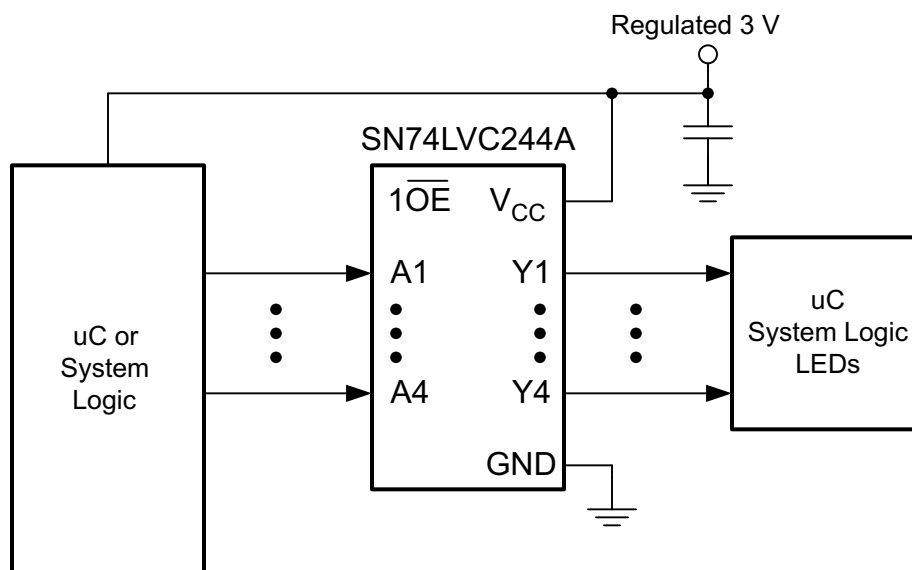
### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

SN74LVC244A is a high drive CMOS device that can be used for a multitude of bus interface type applications where output drive or PCB trace length is a concern. The inputs can accept voltages to 5.5 V at any valid  $V_{CC}$  making it ideal for down translation.

### 9.2 Typical Application



9-1. Application Schematic

#### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Avoid bus contention because it can drive currents in excess of maximum limits. The high drive will also create fast edges into light loads, so consider routing and load conditions to prevent ringing.

#### 9.2.2 Detailed Design Procedure

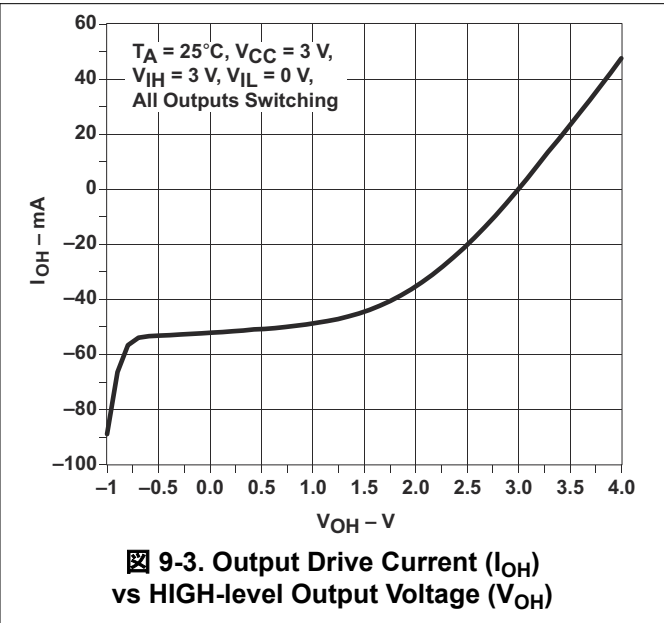
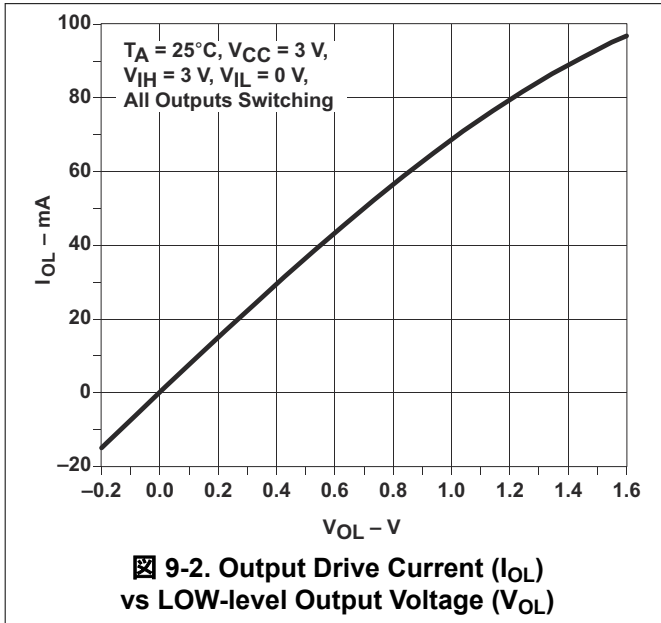
##### 1. Recommended Input Conditions:

- For rise time and fall time specification, see  $(\Delta t/\Delta V)$  in the [セクション 6.3](#) table.
- For specified high and low levels, see  $(V_{IH}$  and  $V_{IL})$  in the [セクション 6.3](#) table.
- Inputs are overvoltage tolerant allowing them to go as high as  $(V_I \text{ max})$  in the [セクション 6.3](#) table at any valid  $V_{CC}$ .

##### 2. Recommended maximum Output Conditions:

- Load currents should not exceed  $(I_O \text{ max})$  per output and should not exceed (Continuous current through  $V_{CC}$  or GND) total current for the part. These limits are located in the [セクション 6.1](#) table.
- Outputs should not be pulled above  $V_{CC}$ .

### 9.2.3 Application Curves



## 10 Power Supply Recommendations

The power supply may be any voltage between the MIN and MAX supply voltage rating located in the [セクション 6.3](#) table.

Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A  $0.1\ \mu\text{F}$  capacitor is recommended for devices with a single supply. If there are multiple  $V_{CC}$  terminals, then  $0.01\ \mu\text{F}$  or  $0.022\ \mu\text{F}$  capacitors are recommended for each power terminal. It is permissible to parallel multiple bypass capacitors to reject different frequencies of noise. Multiple bypass capacitors may be paralleled to reject different frequencies of noise. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

## 11 Layout

### 11.1 Layout Guidelines

Inputs should not float when using multiple bit logic devices. In many cases, functions or parts of functions of digital logic devices are unused. Some examples include situations when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 11-1](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally, they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient.

### 11.2 Layout Example



**Figure 11-1. Layout Diagram**

## 12 Device and Documentation Support

### 12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
すべての商標は、それぞれの所有者に帰属します。

### 12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC244ADBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ADBRE4	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ADBRG4	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ADGVR	ACTIVE	TVSOP	DGV	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ADW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC244A	<a href="#">Samples</a>
SN74LVC244ADWE4	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC244A	<a href="#">Samples</a>
SN74LVC244ADWG4	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC244A	<a href="#">Samples</a>
SN74LVC244ADWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LVC244A	<a href="#">Samples</a>
SN74LVC244ADWRG4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC244A	<a href="#">Samples</a>
SN74LVC244AN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74LVC244AN	<a href="#">Samples</a>
SN74LVC244ANSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC244A	<a href="#">Samples</a>
SN74LVC244APW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWE4	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWG4	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWRE4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWRG3	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWRG4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWT	ACTIVE	TSSOP	PW	20	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244APWTE4	ACTIVE	TSSOP	PW	20	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC244APWTG4	ACTIVE	TSSOP	PW	20	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ARGYR	ACTIVE	VQFN	RGY	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ARGYRG4	ACTIVE	VQFN	RGY	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC244A	<a href="#">Samples</a>
SN74LVC244ARWPR	ACTIVE	X1QFN	RWP	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC244A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LVC244A :**

- Automotive : [SN74LVC244A-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC244ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVC244ADGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC244ADWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74LVC244ADWRG4	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LVC244ANSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LVC244APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVC244APWRG3	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74LVC244APWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVC244APWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVC244ARGYR	VQFN	RGY	20	3000	330.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1
SN74LVC244ARWPR	X1QFN	RWP	20	2000	178.0	13.5	2.85	3.65	0.75	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

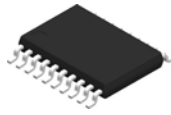

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC244ADBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74LVC244ADGVR	TVSOP	DGV	20	2000	356.0	356.0	35.0
SN74LVC244ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LVC244ADWRG4	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LVC244ANSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74LVC244APWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74LVC244APWRG3	TSSOP	PW	20	2000	364.0	364.0	27.0
SN74LVC244APWRG4	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74LVC244APWT	TSSOP	PW	20	250	356.0	356.0	35.0
SN74LVC244ARGYR	VQFN	RGY	20	3000	356.0	356.0	35.0
SN74LVC244ARWPR	X1QFN	RWP	20	2000	189.0	185.0	36.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVC244ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVC244ADWE4	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVC244ADWG4	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVC244AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74LVC244APW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74LVC244APWE4	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74LVC244APWG4	PW	TSSOP	20	70	530	10.2	3600	3.5



4220206/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



# DB0020A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/B 08/2019

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

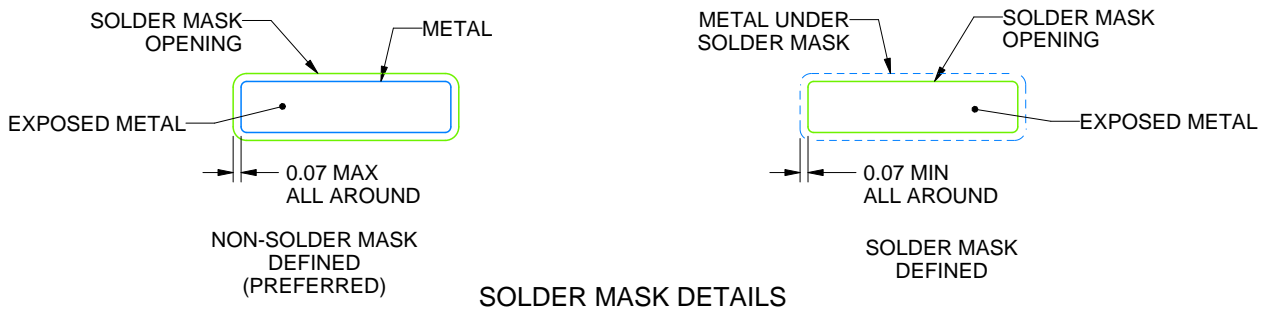
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## GENERIC PACKAGE VIEW

**RGY 20**

**VQFN - 1 mm max height**

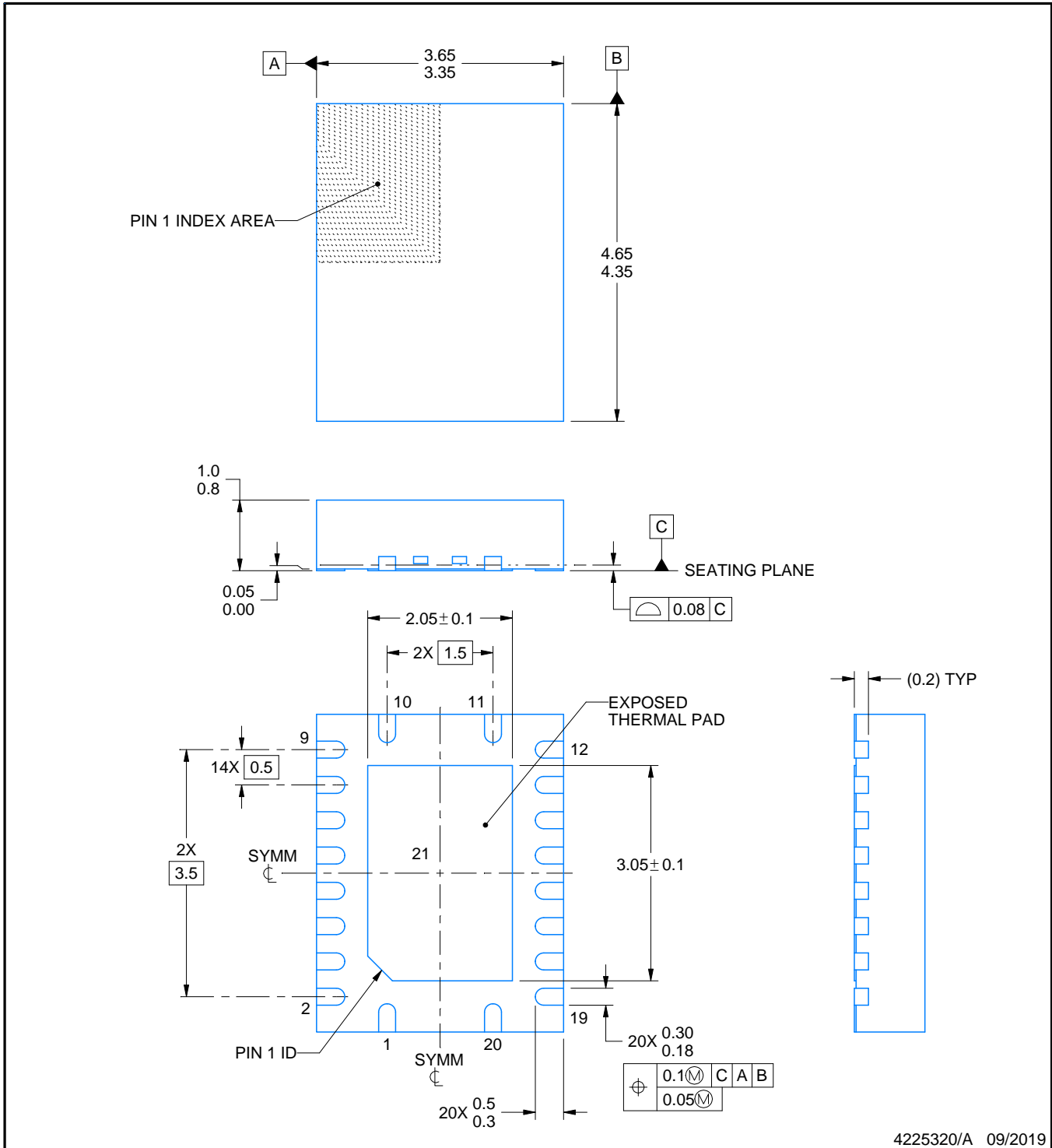
3.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4225264/A



4225320/A 09/2019

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

4225320/A 09/2019

NOTES: (continued)

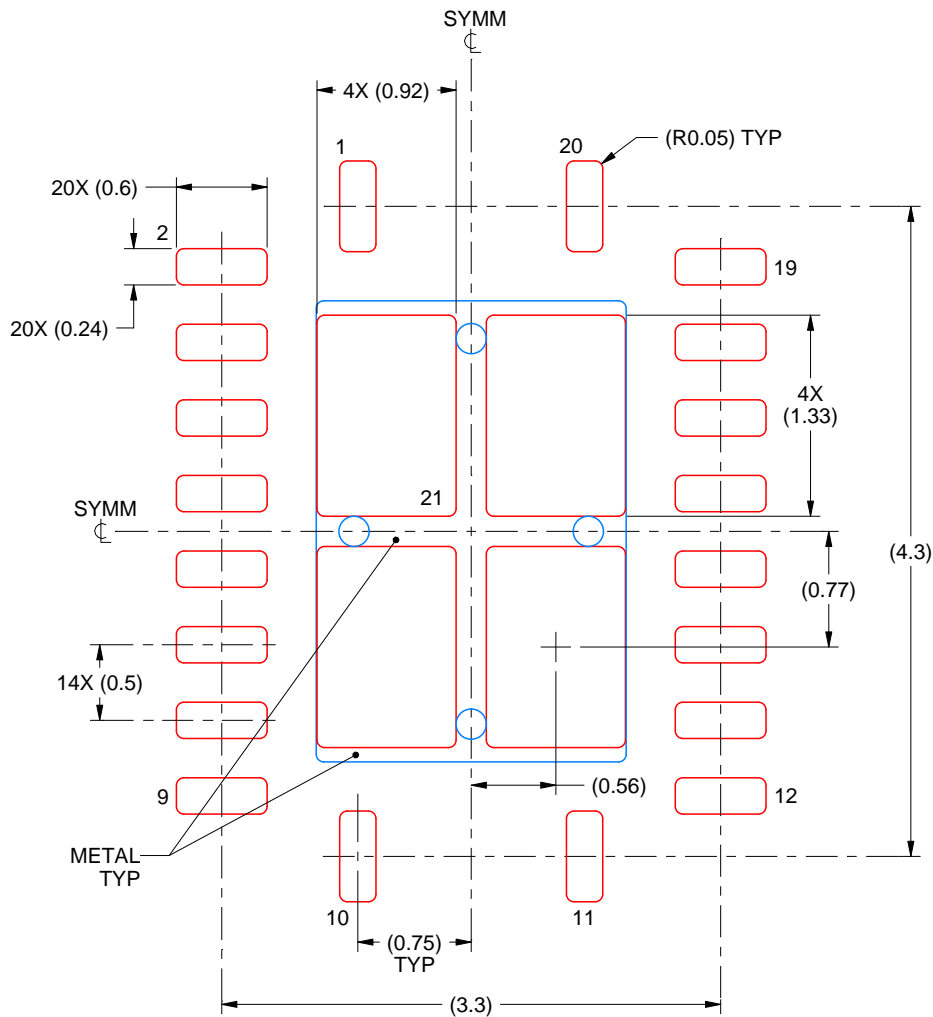
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.125 mm THICK STENCIL

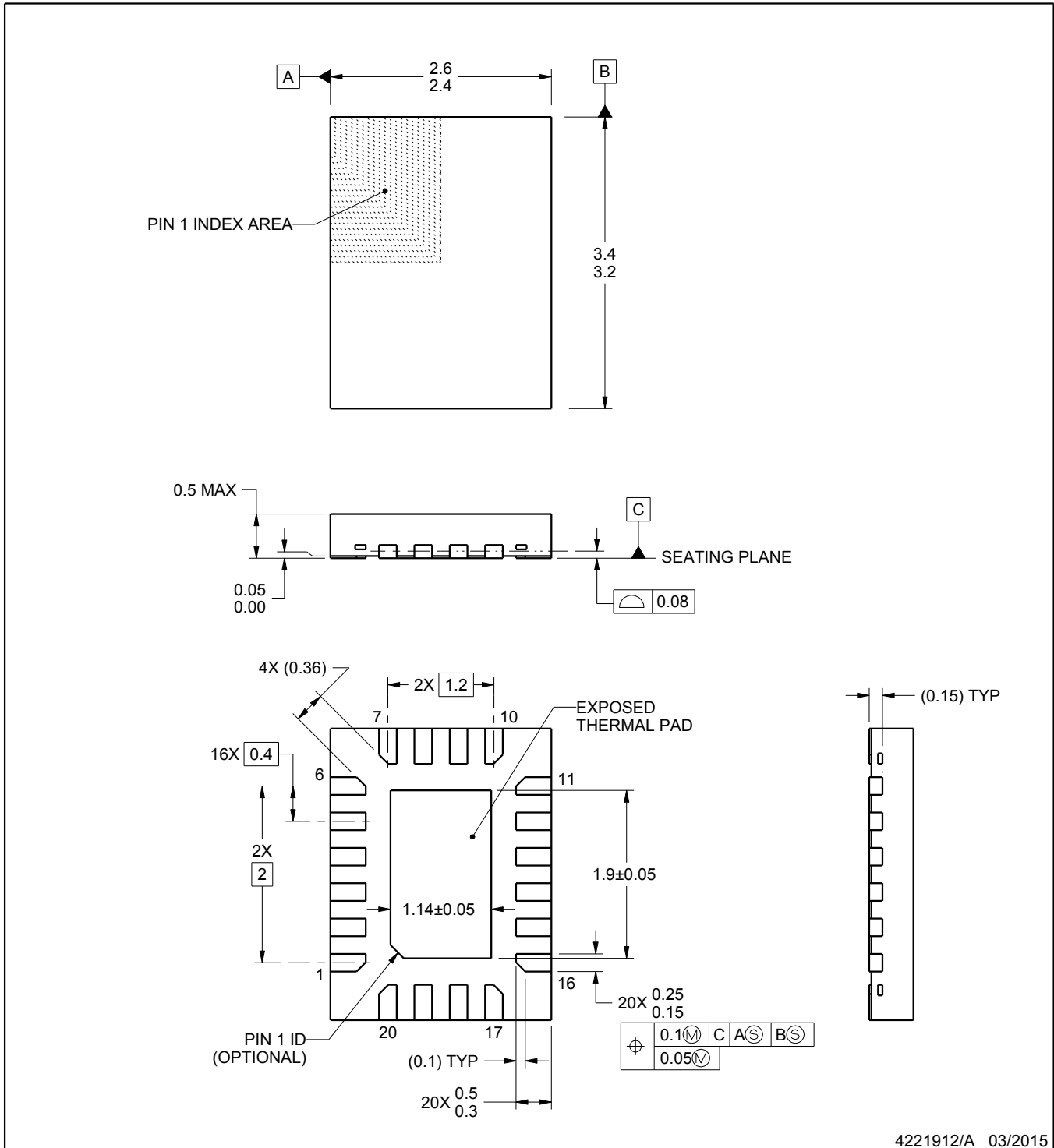
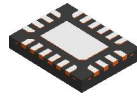
EXPOSED PAD 21  
 78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
 SCALE:20X

4225320/A 09/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.





4221912/A 03/2015

NOTES:

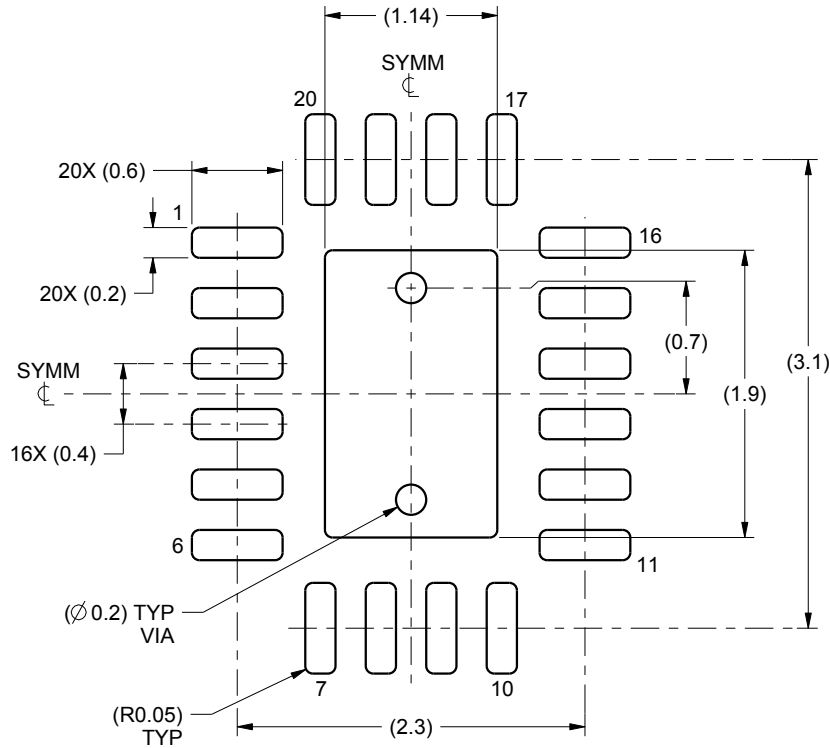
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

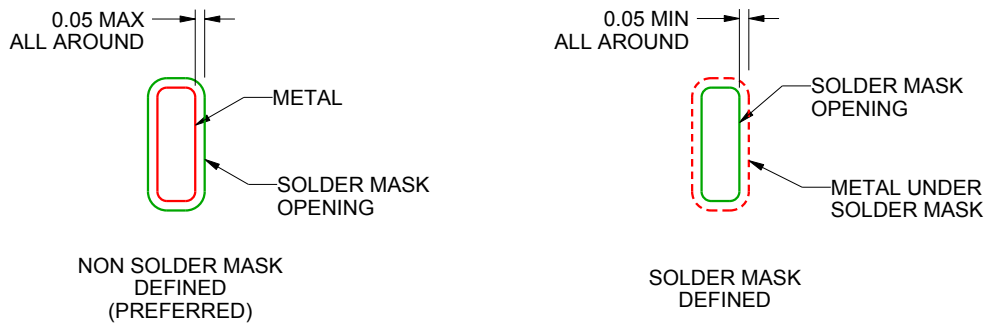
RWP0020A

X1QFN - 0.5 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:20X



SOLDER MASK DETAILS

4221912/A 03/2015

NOTES: (continued)

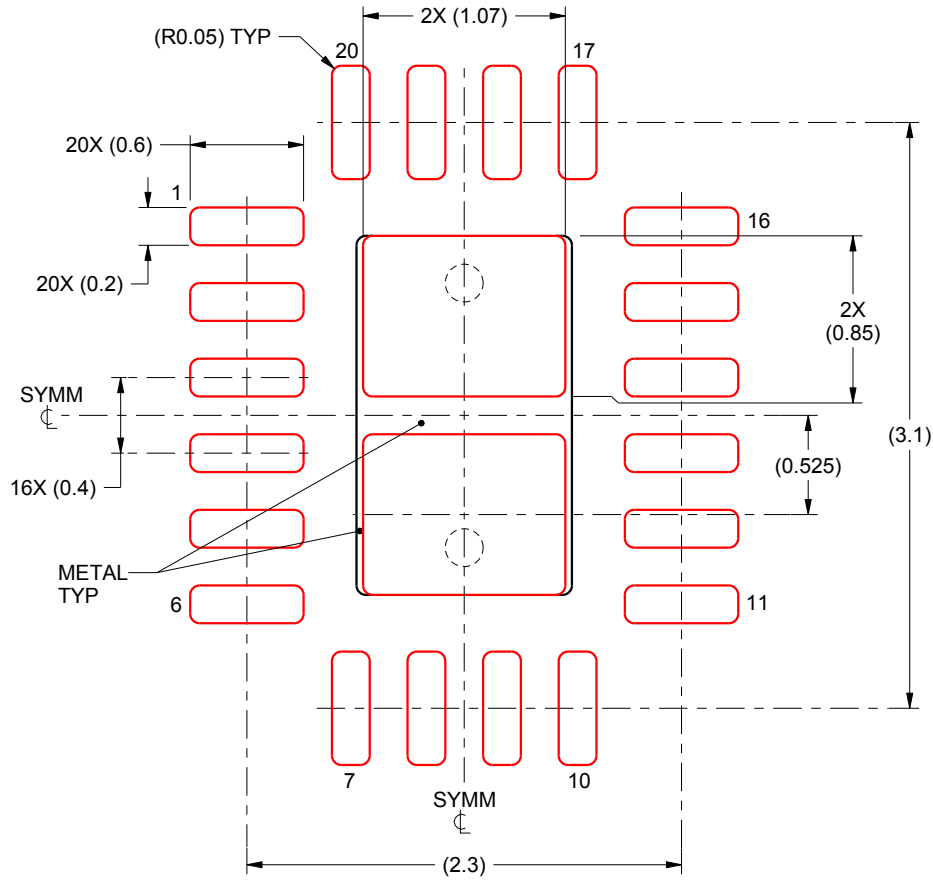
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

RWP0020A

X1QFN - 0.5 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD  
84% PRINTED SOLDER COVERAGE BY AREA  
SCALE:25X

4221912/A 03/2015

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.

## 重要なお知らせと免責事項

TI は、技術データと信頼性データ(データシートを含みます)、設計リソース(リファレンス・デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、または [ti.com](#) やかかる TI 製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、TI はそれらに異議を唱え、拒否します。

郵送先住所 : Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2024, Texas Instruments Incorporated